

USB Power Delivery Controller

VIDWriter 1.0.0.0 Instruction Manual

Introduction

VIDwriter 1.0.0.0 is an instructional tool that generates flash memory image data for Renesas USB Power Delivery turnkey solutions: JP214 / RTK-251-SinkAdapter and RTK-251-SinkCharger-ISL9238C.

Target Device

100W USB Type-C® Input Power Converter: JP214 / RTK-251-SinkAdapter

USB Power Delivery Controller: R9A02G011

Buck-Boost Voltage Regulator: ISL95338 (substitute product: RAA489800)

100W USB Type-C® Charger or MAX 60W Power Bank: RTK-251-SinkCharger-ISL9238C

USB Power Delivery Controller: R9A02G011

On-Board Charger: ISL9238C

Target VIDWriter

VIDWriter 1.0.0.0 version: 1.0.0.0

Related Document

Use this document in combination with the following documents.

The related documents indicated in this publication may include preliminary versions. However, preliminary versions are not marked as such.

- R9A02G011 Data Sheet: R19DS0088EJ
- R9A02G011 User's Manual: R19UH0102EJ
- E1 Emulator E20 Emulator User's Manual: R20UT0398EJ
- E2 Emulator Lite User's Manual: R20UT3240EJ
- E1/E20 Emulator, E2 Emulator Lite Additional Document for User's Manual (Notes on Connection of RL78): R20UT1994EJ
- Renesas Flash Programmer V3.13 Flash memory programming software User's Manual: R20UT5312EJ

- R9A02G011 JP214 / RTK-251-SinkAdapter Instruction Manual: R19AN0246EJ
- R9A02G011 RTK-251-SinkCharger-ISL9238C Instruction Manual: R19AN0266EJ

Contents

1. Overview.....	4
1.1 Functions.....	4
1.2 Operating Environment	4
1.2.1 Host PC	4
1.2.2 Supported OS.....	4
2. Operation Method.....	5
2.1 Setup the VIDWriter	5
2.2 View Description.....	5
2.2.1 Without Battery in Field B.....	6
2.2.2 With Battery in Field B.....	8
2.3 Sourcing mode	11

FIGURES

Figure 2-1 Main window for VIDWriter 1.0.0.0	5
Figure 2-2 Main window for VIDWriter 1.0.0.0 after Product Configuration	6
Figure 2-3 Main window for VIDWriter 1.0.0.0 when press Schematic Setting Preview.....	7
Figure 2-4 Main window for VIDWriter 1.0.0.0 after Product Configuration	8
Figure 2-5 The Field E and the EVB setting vs “Board” configuration	9
Figure 2-6 The Field E and the EVB setting vs “BMS” configuration	9
Figure 2-7 The Field E and the EVB setting vs “Manual” configuration	10
Figure 2-8 Main window for VIDWriter when press Schematic Setting.....	10

TABLES

Table 2-1 Evaluation boards for each project.....	6
Table 2-2 The supported maximum Type-C sourcing PD Power for Sourcing mode	11
Table 2-3 PDO list	12

1. Overview

1.1 Functions

- Change VID and PID parameters in FW if need.
- Generate Flash memory image data.
- Indicates the HW configuration required after feature selection.

1.2 Operating Environment

1.2.1 Host PC

- Processor: 1 GHz or faster
- Main memory: At least 1 Gbyte
- Display: Resolution of 1024 x 768 or higher and 65,536 or more colors

1.2.2 Supported OS

- Windows 10 (32-bit or 64-bit)
- Windows 11 (32-bit or 64-bit)

Remark:

Microsoft.NET Framework 4.6.1 or later has to be installed.

2. Operation Method

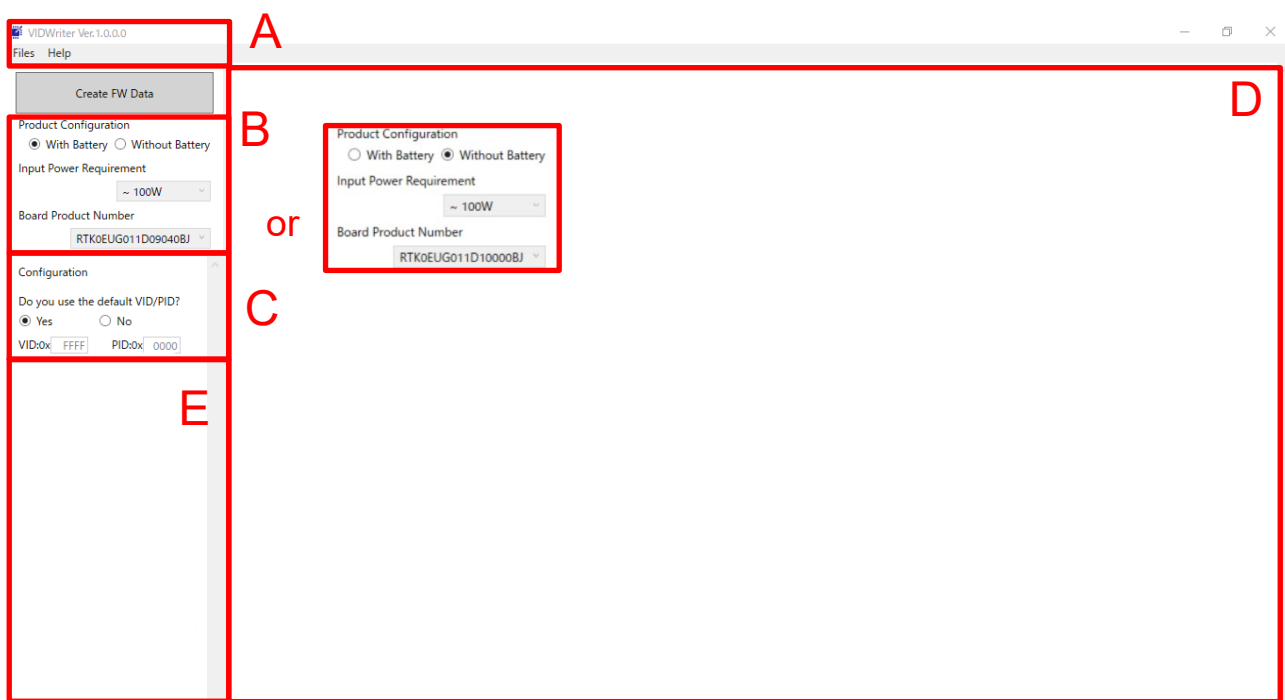
2.1 Setup the VIDWriter

- 1) Install Microsoft .NET Framework 4.6.1 or later.
- 2) Uses exe file including in this unzip directory.
This tool can work without installation. DO NOT change directory structure in the unzipped data.

2.2 View Description

When you run VIDWriter 1.0.0.0, the window as shown Figure 2-1 will display.

Figure 2-1 Main window for VIDWriter 1.0.0.0



- 1) Menu Bar
You can check Tool version and FW package version in “Help” -> “About”.
- 2) Field B to select the required feature
Choose the features that match your required behavior in this field. Once selected, the recommended turnkey solution will be displayed in Field D and the possible configurations will be shown in Field E.
And also, the recommended board product number is indicated in this field.
- 3) Field C to set VID/PID number.
If you want to use your own hexadecimal VID and PID numbers instead of the default VID/PID(0xFFFF/0x0000) numbers set in this field, overwrite your own numbers to this field.
Otherwise, leave VID: FFFF and PID: 0000.
- 4) Window for the Renesas recommended turnkey solution
When selected the feature, Field D shows the Renesas recommended turnkey solution as shown in Figure 2-2, and Figure 2-4.

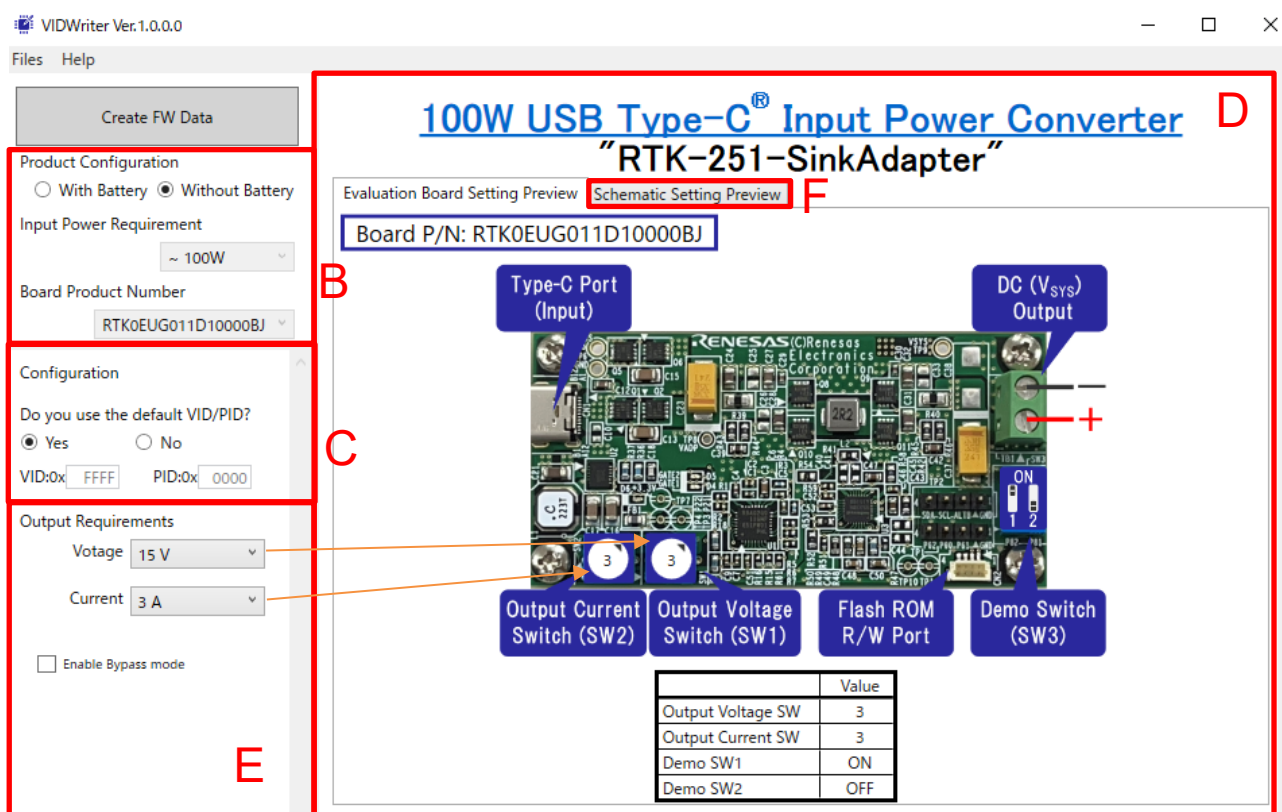
Table 2-1 Evaluation boards for each project

	Maximum power		
	~100 W	~ 140 W	~ 240 W
w/ Battery	RTK-251-SinkCharger-ISL9238C	Under development	
w/o Battery	JP214 / RTK-251-SinkAdapter	-	-

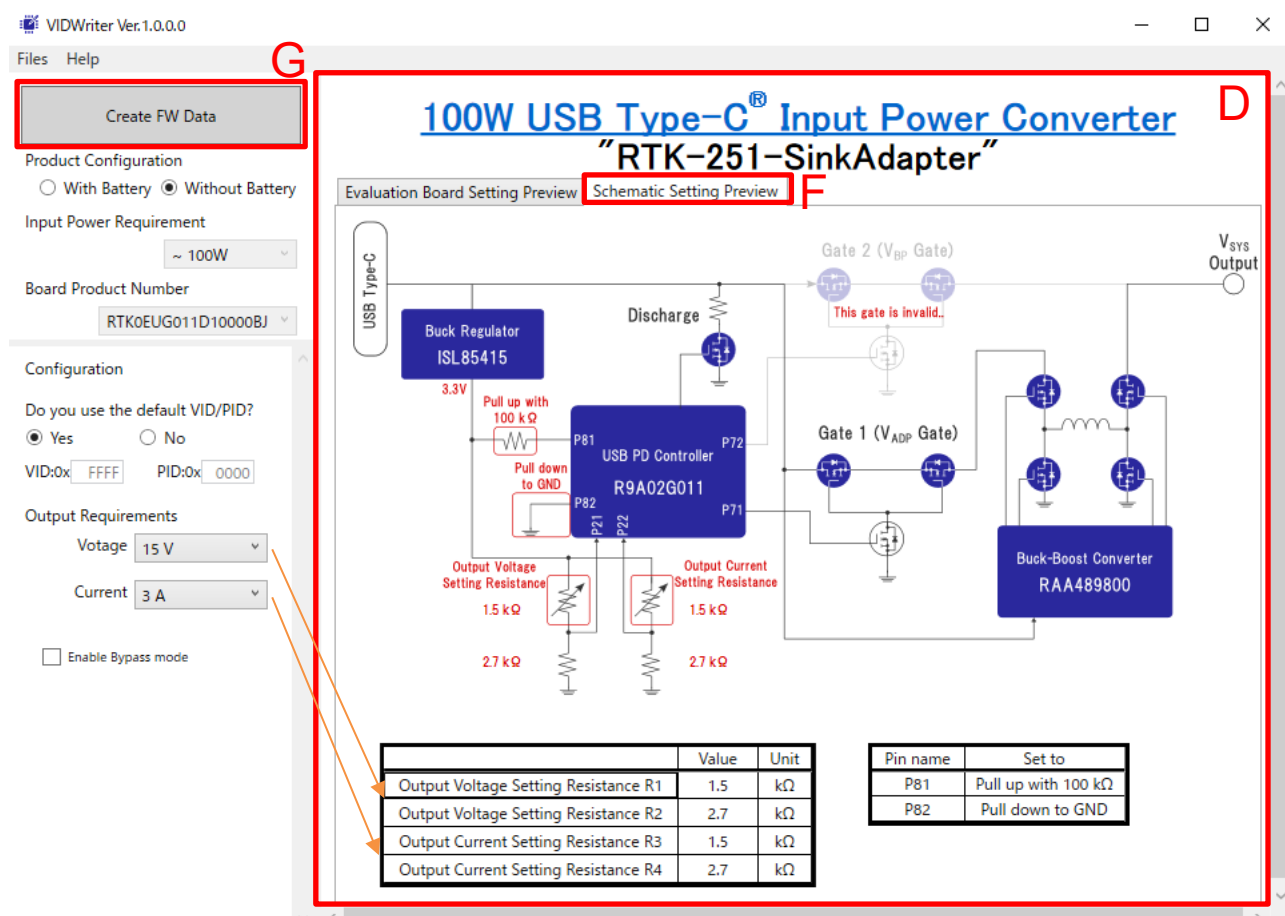
2.2.1 Without Battery in Field B

If user selects “Without Battery” in Field B, RTK-251-SinkAdapter will be displayed as Renesas recommended turnkey solution in Field D.

Figure 2-2 Main window for VIDWriter 1.0.0.0 after Product Configuration



- Field E configures the turnkey solution recommended by Renesas.
When select the setting for both DC output voltage and maximum output current of this EVB, from the drop-down list in this field, Field D indicates the appropriate physical settings on the EVB. Next, set the switches on the board according to this picture.
- Also, if you require to feed USB-C input directly to the DC output on the board, check “Enable Bypass Mode”.
- Press the "Schematic Setting Preview" F tab in Field D to display the recommended turnkey schematic with appropriated parameters, such as Figure 2-3.

Figure 2-3 Main window for VIDWriter 1.0.0.0 when press Schematic Setting Preview

8) Finally, when you press the "Create FW Data" button, a file save dialog will be displayed. The default storage location is the "My Documents" folder. You can change the save location and file name of the ROM image as you like. If you rewrite this ROM image to R9A02G011 on EVB, please use Renesas Flash Programmer V3 as programming software. See the documents below.

- Renesas Flash Programmer V3.13 Flash memory programming software User's Manual (R20UT5312EJ)
- List of MCUs supported by Renesas Flash Programmer V3 (R20UT3599EJ)
- On the development of flash memory programmer by user, refer to **RL78 microcontrollers (RL78 Protocol A) Programmer Edition Application Note (R01AN0815EJ)**.

2.2.2 With Battery in Field B

If the user selects “With Battery” in Field B, RTK-251-SinkCharger-ISL9238C will be displayed as Renesas recommended turnkey solution in Field D and RTK0EUG011D09040BJ in Board Product Number field.

5) Field E configures the turnkey solution recommended by Renesas.

Field E is used to set the Full, Empty, Max Charging Current, and Max sourcing PDP (DRP mode).

There are three operating modes; “Board”, “BMS”, and “Manual”. The default firmware uses “Board” mode, in which the switches on the board configure the EVB parameters. “BMS” sets EVB parameters by battery status information from BMS. “Manual” can set EVB parameters directly. After setting in Field E, Field D indicates the appropriate physical settings on the EVB. Next, set the switches on the board according to this picture.

Note: In order to use “BMS” or “Manual” modes, FW on the board must be rewritten by this VIDwriter 1.0.0.0-generated FW. If operating mode is changed to “Board” from “BMS” or “Manual”, FW on the board also must be rewritten by this VIDwriter 1.0.0.0-generated FW.

Figure 2-4 Main window for VIDWriter 1.0.0.0 after Product Configuration

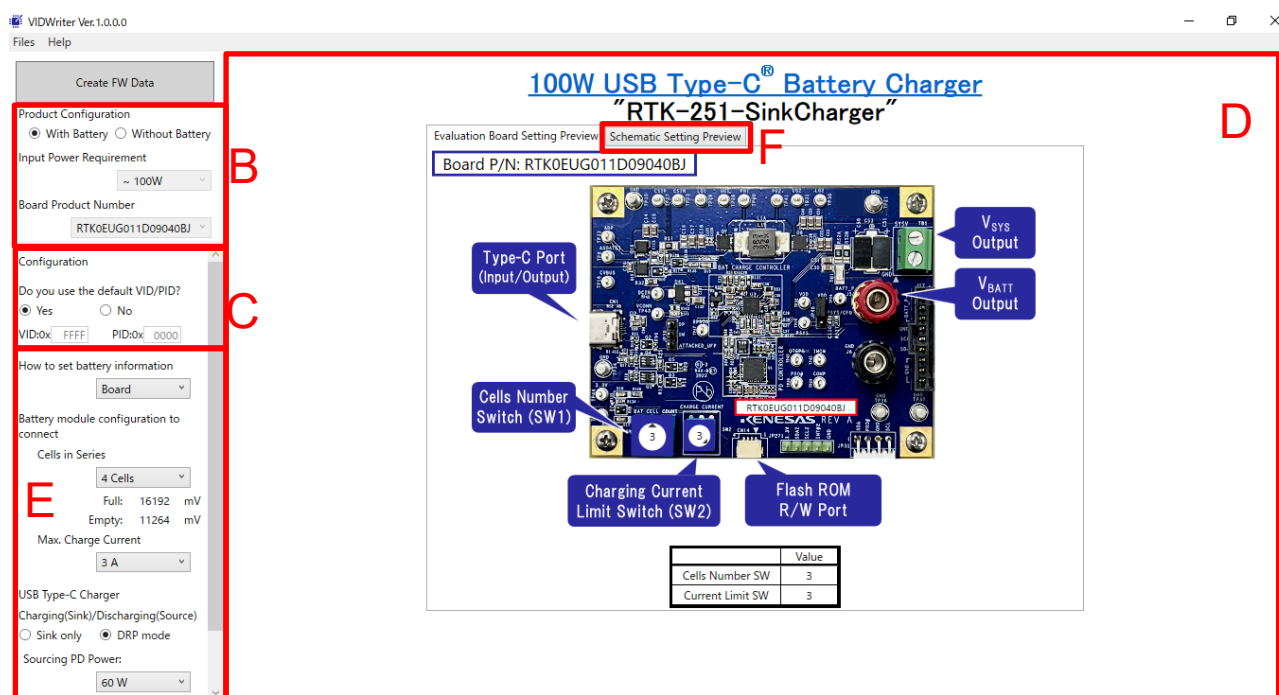
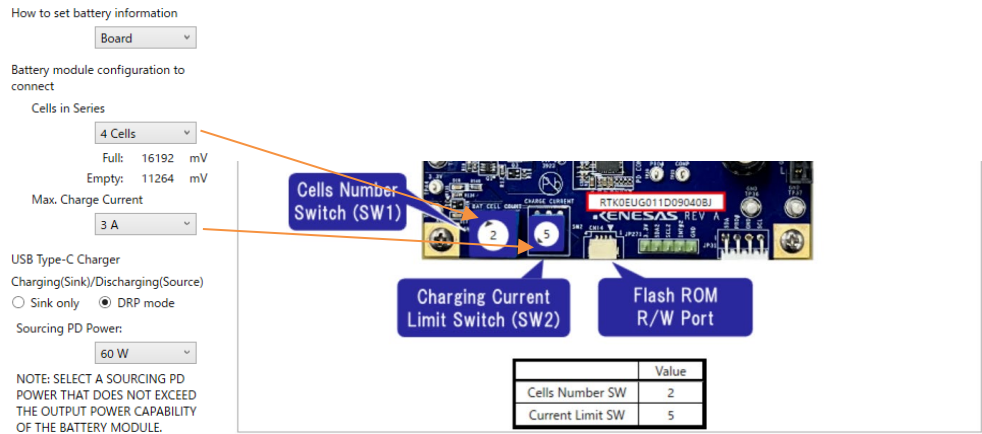


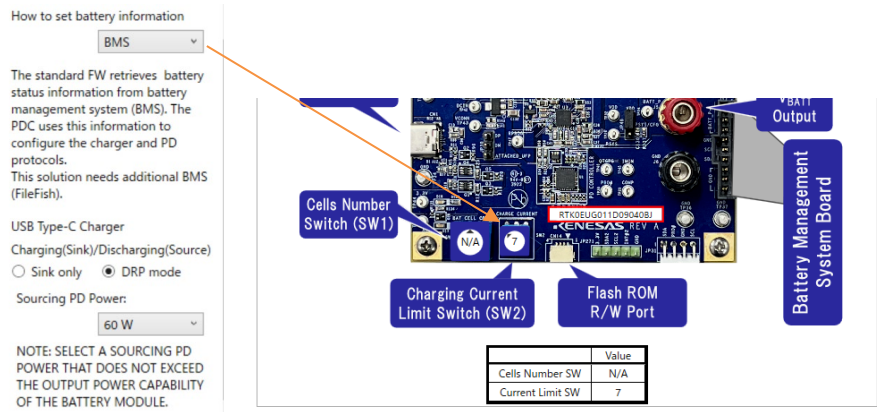
Figure 2-5 The Field E and the EVB setting vs “Board” configuration



“Full” indicates the maximum battery charging voltage. “Empty” indicates the voltage at which the charger will trickle charge the battery at a low current level if VBAT is below that value.

If the user wants to achieve power bank function with RTK-251-SinkCharger-ISL9238C, please select DRP mode. Otherwise, select Sink only. In the sourcing mode of Power Bank operating, the user selects the maximum sourcing PD Power from the drop-down list. See Section 2.3 about the maximum sourcing PDP.

Figure 2-6 The Field E and the EVB setting vs “BMS” configuration



In “BMS” setting, this EVB frequently retrieves battery related information from RAJ240100 Filefish EVM. In this operating mode, this EVB uses the information obtained from RAJ240100 Filefish EVM instead of SW2 value to configure the On-Board Charger.

If the user wants to achieve power bank function with RTK-251-SinkCharger-ISL9238C, please select DRP mode. Otherwise, select Sink only. In this operating mode, the FW cannot recognize the MaxSysVol, MinSysVol, and Charging Current Limits until R9A02G011 retrieves the battery information from BMS. So, VIDWriter 1.0.0.0 cannot define the true max sourcing PD Power under sourcing mode. Therefore, the user should set the appropriate Max sourcing PD Power that battery module can support. See Section 2.3 about how to set maximum sourcing PDP.

Figure 2-7 The Field E and the EVB setting vs “Manual” configuration

How to set battery information

Manual

Battery module configuration to connect

Cells in Series: 4 Cells

Full: 4048 mV/Cell
Empty: 2816 mV/Cell

Full: 16192 mV
Empty: 11264 mV

Charging Current Limit: 3000 mA

USB Type-C Charger

Charging(Sink)/Discharging(Source)

☐ Sink only ☒ DRP mode

Sourcing PD Power: 60 W

NOTE: SELECT A SOURCING PD POWER THAT DOES NOT EXCEED THE OUTPUT POWER CAPABILITY OF THE BATTERY MODULE.

	Value
Cells Number SW	N/A
Current Limit SW	0

If there is no suitable charging current value on SW2 and/or user does not want to set “Full” and “Empty” as standard values, user needs to set SW2 to SW position 0 and set the expected charging current value, “Full” and “Empty”. “Full” indicates the maximum battery charging voltage. “Empty” indicates the voltage at which the charger will trickle charge the battery at a low current level if VBAT is below.

If the user wants to achieve power bank function with RTK-251-SinkCharger-ISL9238C, please select DRP mode. Otherwise, select Sink only. In the sourcing mode of Power Bank operating, the user selects the maximum sourcing PD Power from the drop-down list. See Section 2.3 about the maximum sourcing PDP.

- 6) Press the "Schematic Setting Preview" F tab in field D and you will see the recommended turnkey schematics with appropriated parameters, such as Figure 2-8.

Figure 2-8 Main window for VIDWriter when press Schematic Setting

	Value	Unit
Cells Number Setting Resistance	316	kΩ
Charging Current Limit Setting Resistance R1	1.5	kΩ
Charging Current Limit Setting Resistance R2	2.7	kΩ

7) Finally, when you press the "Create FW Data" button, a file save dialog will be displayed. The default storage location is the "My Documents" folder. You can change the save location and file name of the ROM image as you like. If you rewrite this ROM image to R9A02G011 on the evaluation board, please use Renesas Flash Programmer V3 as programming software. Refer to the following documents.

- Renesas Flash Programmer V3.13 Flash memory programming software User's Manual (R20UT5312EJ)
- List of MCUs supported by Renesas Flash Programmer V3 (R20UT3599EJ)
- On the development of flash memory programmer by user, refer to **RL78 microcontrollers (RL78 Protocol A) Programmer Edition Application Note (R01AN0815EJ)**.

2.3 Sourcing mode

Note: The RTK-251-SinkCharger-ISL9238C does not have a battery protection circuit on the board, so, Renesas strongly recommends using a battery module with Renesas' Battery Management System to avoid over-discharging under the power bank mode. RTK-251-SinkCharger-ISL9238C can support power bank mode as long as the battery module uses protection circuit to avoid over-discharge, over-temperature, etc. However, this should be done at user's own risk.

Under sourcing mode for Power Bank operating, RTK-251-SinkCharger-ISL9238C supports standard max sourcing PD Power as shown in Table 2-2 based on following formula.

Available sourcing power = MinSysVol X Charging Current Limit X 2

The standard PD Power in FW = Max supply current (3A) X Standard supply voltage (5, 9, 15, or 20V)
= 15, 27, 45, or 60W

The Max sourcing PD Power in FW ≤ Available sourcing power

The max sourcing PDP is calculated by the MinSysVol value and Charging Current Limit value. For example, if the MinSysVol is 11.2V and the charging current limit is 1A, the available sourcing power is 22.4W. As a result, the maximum sourcing PDP of the FW is 15W. When the MinSysVol is 11.2V and the charging current limit is 3A, the available sourcing power is 67.2W. Therefore, the user can choose either 15, 27, 45, or 60W as the Max sourcing PDP. The Max sourcing PDP is calculated by the above formula even though MaxSysVol, MinSysVol, and Charging Current Limits are set manually.

When the operating mode is "BMS", the FW cannot recognize the MaxSysVol, MinSysVol, and Charging Current Limits until R9A02G011 retrieves the battery information from BMS. Therefore, the user should set the appropriate Max sourcing PD Power that battery module can support.

The USB-PD PDO list, which is used on PD negotiation, will be generated by this Max sourcing PDP. If the available sourcing power is less than 15W, RTK-251-SinkCharger-ISL9238C will not support sourcing mode for Power Bank operating.

Also, Max sourcing PDP is limited to 60W because there is no VCONN power on RTK-251-SinkCharger-ISL9238C. To support 100W sourcing PDP, VCONN power should be required on system board to check 5A capability of cable. At that case, FW modification is required. Please ask your Renesas' contact person.

Table 2-2 The supported maximum Type-C sourcing PD Power for Sourcing mode

	1A	2A	3A	4A	5A	6A
2 Cells in series	-	15W	27W	45W	45W	60W
3 Cells in series	15W	27W	45W	60W	60W	60W
4 Cells in series	15W	45W	60W	60W	60W	60W

Table 2-3 PDO list

	PDO1	PDO2	PDO3	PDO4
PDP 15W	5V/3A	-	-	-
PDP 27W	5V/3A	9V/3A	-	-
PDP 45W	5V/3A	9V/3A	15V/3A	20V/2.25A
PDP 60W	5V/3A	9V/3A	15V/3A	20V/3A

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Mar 14, 2024	-	Initial release

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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